



(19)

(11) Publication number: **2000**

Generated Document.

PATENT ABSTRACTS OF JAPAN(21) Application number: **11159841**(51) Intl. Cl.: **H01L 21/304 B24B 37/00**(22) Application date: **07.06.99**

<p>(30) Priority:</p> <p>(43) Date of application publication: 15.12.00</p> <p>(84) Designated contracting states:</p>	<p>(71) Applicant: ASAHI CHEM IND CO L</p> <p>(72) Inventor: KOIKE HISAO IMAUCHI TOSHIO</p> <p>(74) Representative:</p>
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(54) POLISHING PAD

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a polishing pad, with which the surface of a wafer can be polished to a highly flat and highly uniform surface without having risk of peelings, etc., when the surface is polished by the CMP method.

SOLUTION: A polishing pad is not constituted of laminated sheets but rather a single sheet. At one or more locations of the sheet in the thickness direction, gradual hardness decreasing sections G1 and G2, in which the hardness of the sheet decreases toward the backside from the polished surface side, are provided. When this polishing pad is used, the surface of a wafer can be polished to a high planarity and to a highly uniform surface, and risk of peelings, etc., do not exist during use. Therefore, when this polishing pad is used in the polishing of the surface of the wafer by the CMP method, the surface can be polished to a high

*decreasing hardness
section*

planarity and to a highly uniform surface.

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